1N5620GP

SINTERED GLASS JUNCTION PLASTIC RECTIFIER

VOLTAGE: 800V **CURRENT: 1.0A**

GULF SEMI

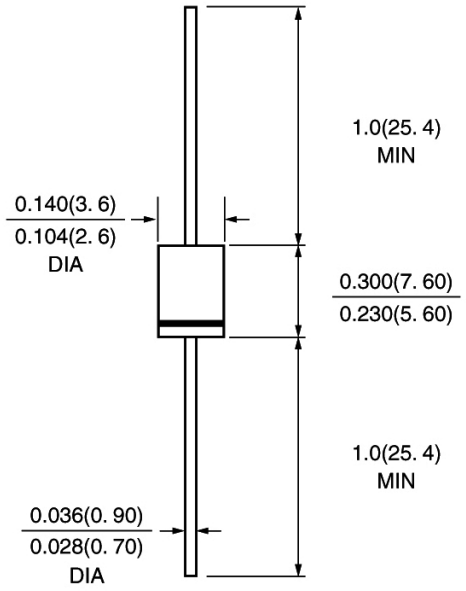
FEATURE

High temperature metallurgically bonded construction
Sintered glass cavity free junction
Low reverse current
Capability of meeting environmental standard of MIL-S-19500
High temperature soldering guaranteed
350°C /10sec/0.375"lead length at 5 lbs tension

MECHANICAL DATA

Terminal: Plated axial leads solderable per MIL-STD 202E, method 208C
Case: Molded with UL-94 Class V-0 recognized Flame Retardant Epoxy
Polarity: color band denotes cathode
Mounting position: any

DO-15\DO-204AC



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(single-phase, half-wave, 60HZ, resistive or inductive load rating at 25°C, unless otherwise stated)

	SYMBOL	1N5620GP	units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	800	V
Maximum RMS Voltage	V_{RMS}	560	V
Maximum DC blocking Voltage	V_{DC}	800	V
Maximum Reverse Breakdown Voltage I_R=50μA	V_{BR}	880	V
Maximum Average Forward Rectified Current 3/8"lead length at Ta=50℃	I_{FAV}	1.0	A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	50	A
Maximum Forward Voltage at Forward Current 3.0A and 25℃	V_F	1.3	V
Maximum DC Reverse Current Ta =25℃ at rated DC blocking voltage Ta =100℃	I_R	1.0 25.0	μA
Maximum Reverse Recovery Time (Note 1)	Trr	2.0	μS
Typical Junction Capacitance (Note 2)	Cj	50.0	pF
Typical Thermal Resistance (Note 3)	Rth(ja)	35.0	℃ /W
Storage and Operating Junction Temperature	Tstg, Tj	-65 to +175	℃

Note:
1. Reverse Recovery Condition If =0.5A, Ir =1.0A, Irr =0.25A
2. Measured at 1.0 MHz and applied reverse voltage of 12.0Vdc
3. Thermal Resistance from Junction to Ambient at 3/8"lead length, P.C. Board Mounted

RATINGS AND CHARACTERISTIC CURVES 1N5620GP

FIG. 1 - FORWARD CURRENT DERATING CURVE

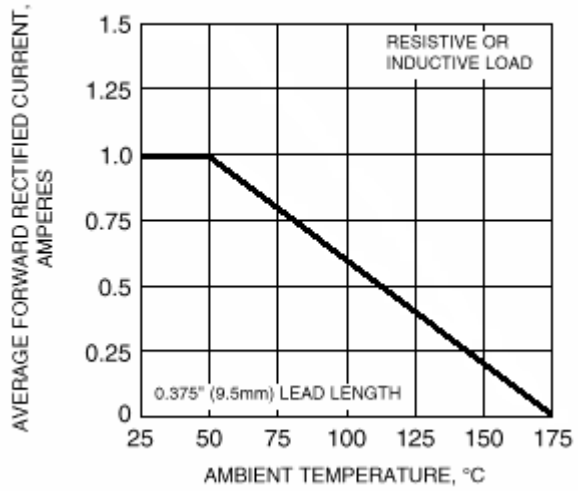


FIG. 2 - MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

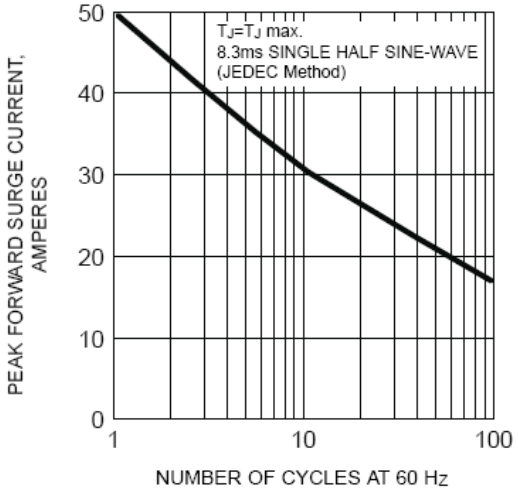


FIG. 3 - TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

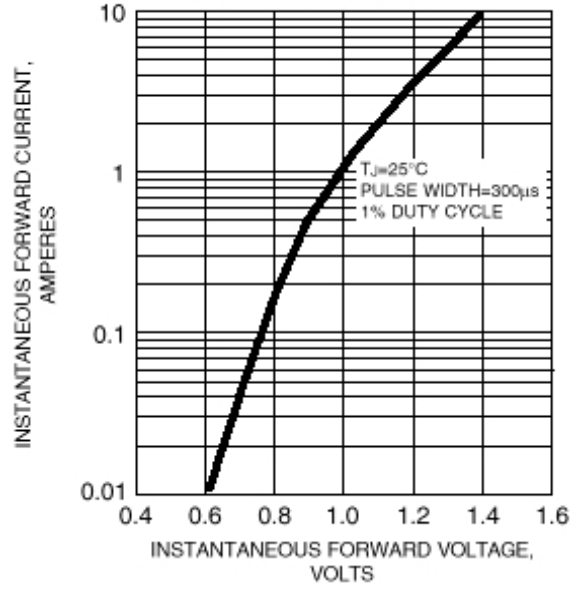


FIG. 4 - TYPICAL REVERSE CHARACTERISTICS

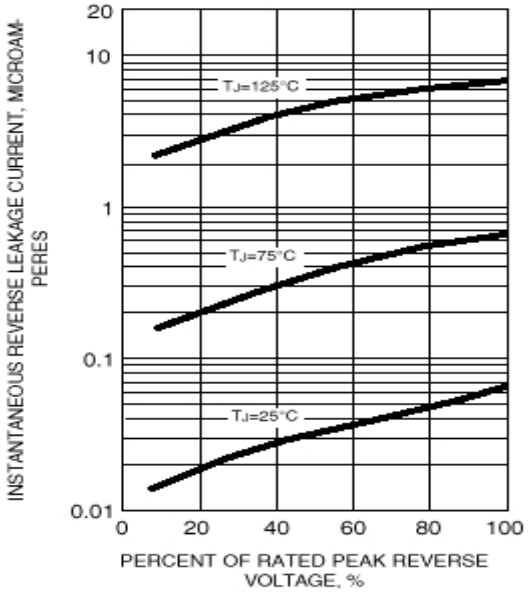


FIG. 5 - TYPICAL JUNCTION CAPACITANCE